

Datos OMNIMATE - Conectores RJ45 RJ45C5 R1D 3.3E4N RL

Weidmüller Interface GmbH & Co. KG
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La gama de productos abarca los diseños siguientes:

- 90° horizontal y 180° vertical
- Bloqueo ascendente/descendente
- Procesos de soldadura THT, THR o SMD
- Amplia gama de diferentes tipos de diseño, también con LED integrados y lengüetas de contacto de apantallado
- Categoría de rendimiento 3 a cat. 6
- Embalaje en bandeja (TY) o en rollo (embalaje en cinta, RL)

Propiedades y ventajas:

- Rango de temperaturas ampliado de -40°C a +85°C para ofrecer la máxima capacidad de rendimiento
- Capa de oro reforzada (30 µ") para ofrecer una protección mejorada frente a la corrosión
- La distancia de al menos 3 mm garantiza un resultado de soldadura perfecto

Datos generales para pedido

Tipo	RJ45C5 R1D 3.3E4N RL
Código	2562910000
Versión	Conector para placa c.i., Conectores RJ45, Cat. 5 , Conexión por soldadura THT/THR, 90°, Opción de bloqueo: inferior, Anilla de apantallado: 6 tabs, 30-80 µ" Ni / 30- µ" Au , LED: No, Número de polos: 8, Tape
GTIN (EAN)	4050118571936
U.E.	200 Pieza
Embalaje	Tape

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Datos técnicos

Dimensiones y pesos

Anchura	15,7 mm	Anchura (pulgadas)	0,618 inch
Altura	17,06 mm	Altura (pulgadas)	0,672 inch
Altura construcción baja	13,76 mm	Profundidad	21,3 mm
Profundidad (pulgadas)	0,839 inch	Peso neto	10 g

Temperaturas

Temperatura de almacenamiento, max.	85 °C	Temperatura de almacenamiento, min.	-40 °C
Temperatura de servicio, max.	85 °C	Temperatura de servicio, min.	-40 °C

Conformidad medioambiental del producto

REACH SVHC	Lead 7439-92-1
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Especificaciones del sistema

Angulo de salida	90°	Anilla de apantallado	6 tabs
Apantallamiento	Sí	Categoría	Cat. 5
Ciclos de enchufado	750	Diámetro de la perforación (D)	0,9 mm
Familia del producto	Datos OMNIMATE - Conectores RJ45	LED	No
Longitud del terminal de soldadura (l)	3,3 mm	Material del apantallamiento	Latón
Modo de conexión	8 núcleos	Montaje sobre placas c.i.	Conexión por soldadura THT/THR
Número de polos	8	Número de terminales de soldadura por polo	1
Opción de bloqueo	inferior	Paso en mm (P)	1,27 mm
Paso en pulgadas (P)	0,05 inch	Superficie de apantallado	niquelado
Tipo de conexión	Conector hembra	Tipo de protección	IP20
Tolerancia de diámetro de la perforación (D)	± 0,1 mm	Tolerancia de longitud del pin de soldadura	+0,5 / -0,5 mm

Propiedades eléctricas

Intensidad nominal	1,5 A	Resistencia a tensiones eléctricas, contacto/contacto	1000 V AC
Resistencia de aislamiento	1000 MΩ at 500 V DC	Tensión nominal	125 V AC

Datos del material

Materiales aislantes	PA 9T	Color	negro
Carta de colores (similar)	RAL 9011	Grupo de materiales aislantes	II
CTI	≥ 500	Resistencia de aislamiento	1000 MΩ at 500 V DC
Moisture Level (MSL)	1	Grado inflamabilidad según UL 94	V-0
Material del contacto	Fósforo, bronce	Superficie de contacto	Oro sobre níquel
Estructura de capas del contacto del conector	30-80 μ" Ni / 30- μ" Au	Temperatura de almacenamiento, min.	-40 °C
Temperatura de almacenamiento, max.	85 °C	Temperatura de servicio, min.	-40 °C
Temperatura de servicio, max.	85 °C		

Embalaje

Embalaje	Tape	Longitud de VPE	0 m
Anchura VPE	0 m	Altura de VPE	0 m
Diámetro de bobina de cinta Ø (A)	330 mm	Resistencia superficial	Rs = 10 ⁹ - 10 ¹² Ω

Fecha de creación 3 de julio de 2019 8:42:10 CEST

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Datos técnicos

Clasificaciones

ETIM 6.0	EC002637	eClass 6.2	27-25-05-04
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02

Homologaciones en línea

Homologaciones



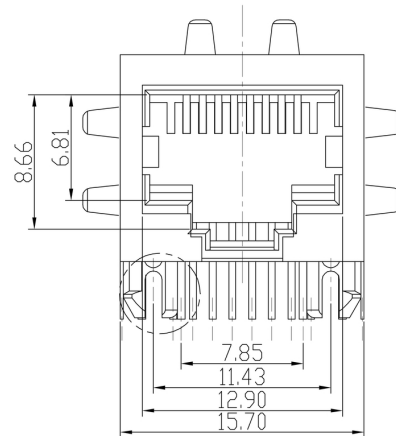
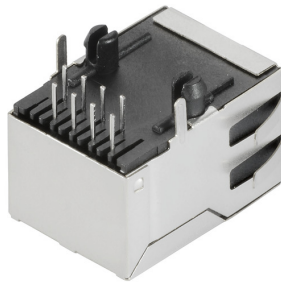
ROHS Conformidad

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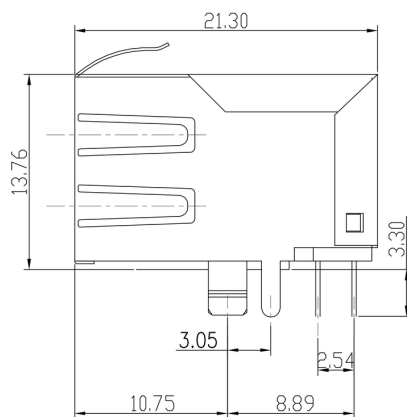
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Dibujos

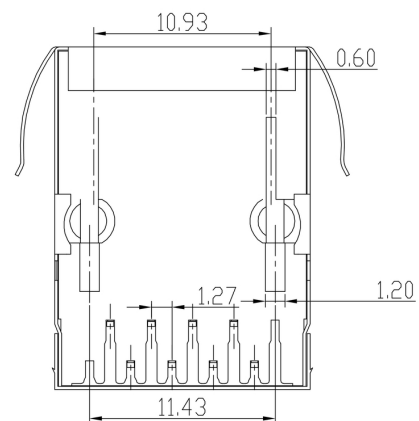
Dibujo acotado



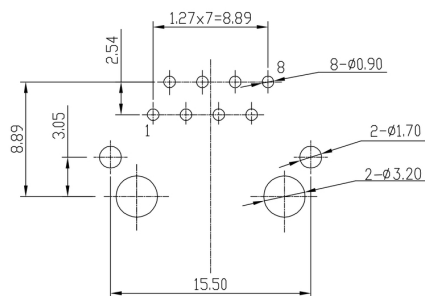
Dibujo acotado



Dibujo acotado



Diseño de la placa de circuito impreso



PCB LAYOUT

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Dibujos

Ventaja del producto



Process-optimised packaging
Tape-on-reel or tray

Ventaja del producto

Ventaja del producto



Trouble-free assembly
Short, chamfered solder pins



Suitable for all soldering processes
SMT, THT or THR

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Dibujos

Leyenda

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Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.